

# Heterogeneous Multi-Core SOC (HMC-SOC) Architectures

**Mark McDermott** 

Fall 2009

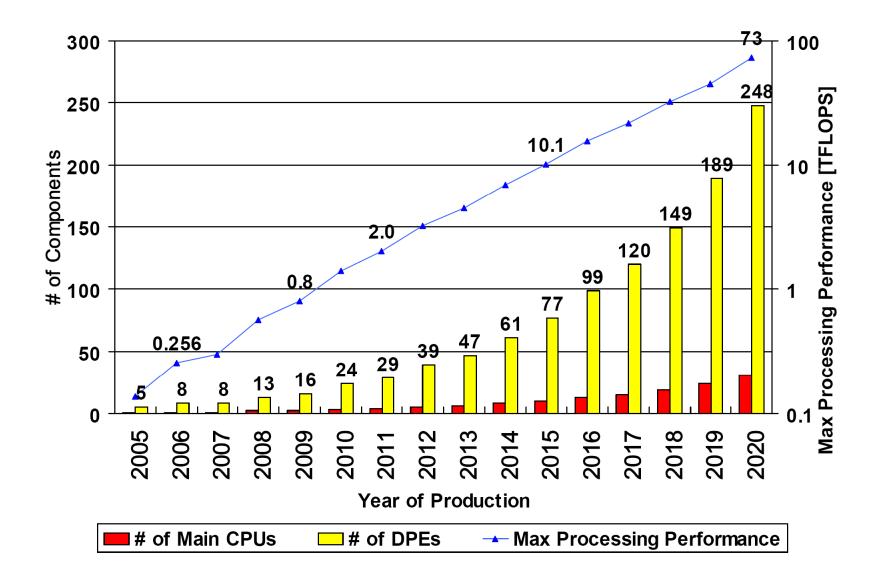


# **Agenda**

- Market prediction
- Architectures of three HMC-SOC platforms:
  - Atmel DIOPSIS 940HF SOC
  - Texas Instruments OMAP
  - IBM Cell Broadband Processor
- HMC-SOC Bus Architectures
  - AMBA AXI
  - IBM Cell Element Interconnect Bus (EIB)
  - Network on Chip Architectures (NOC)

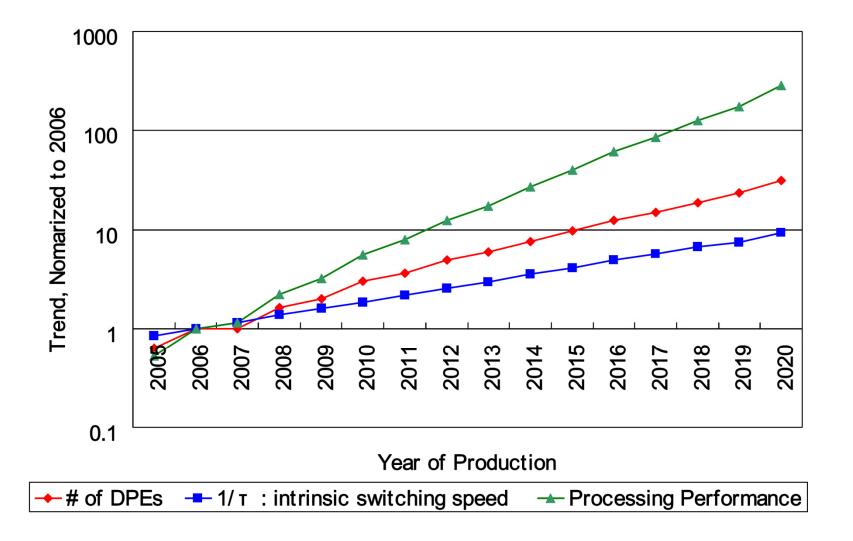


# 2006 ITRS Prediction: CPUs vs. Data Processing Engines



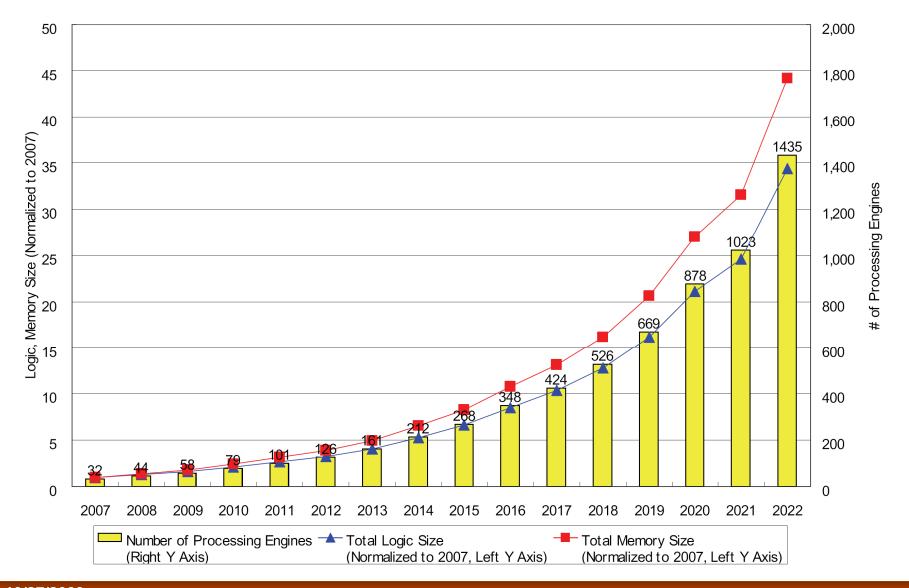


# 2006 ITRS Prediction: Processing Perf. vs. Transistor Perf.





# **2007 ITRS Prediction: Data Processing Engines**





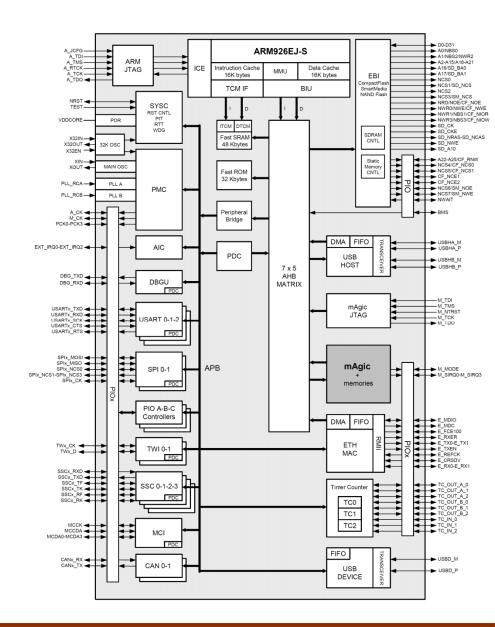
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### **DIOPSIS 940 HF MPSOC**

- Dual-core processing platform for audio, speech processing, automotive sound and robotics applications. The two cores:
  - ARM926EJ-S RISC microprocessor.
  - 40 bit Floating-point Magic DSP
    - Provides high dynamic range and maximum numerical precision.
- Synchronization between the two processors can be either based on interrupts, software polling or semaphores.



Courtesy Atmel, Inc.

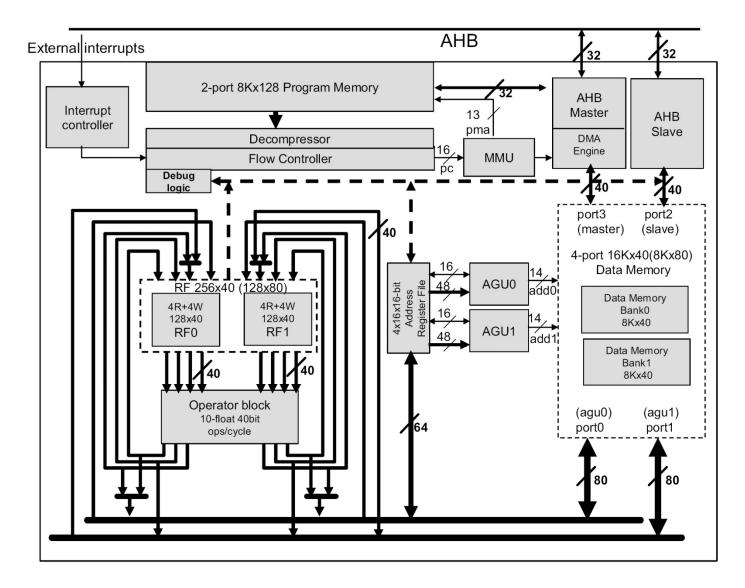


### **VLIW DSP**

- The MagicV VLIW DSP is the numeric processor of D940HF. It operates on IEEE 754 40-bit extended precision floating-point and 32-bit integer numeric format.
- Main components of the DSP subsystem are:
  - Core processor
  - On-chip memories
  - DMA engine and its AHB master and slave interfaces.
  - Operators block
  - Register file
  - Multiple address generation unit
  - Program decoding and sequencing unit
- ARM processor boots the DSP from its Flash memory.



# **VLIW DSP Block Diagram**





# **VLIW DSP (cont)**

- The DSP is a Very Long Instruction Word engine, that works like a RISC machine by implementing triadic computing operations on data coming from the register file and data move operations between the local memories and the register file
  - Memory System contains 16K\*40-bit on-chip memory locations supporting up to 6 accesses/cycle. 4-accesses/cycle are reserved for the activities driven by Multiple Address Generation unit
- Operators are pipelined for maximum performance. The pipeline depth depends on the operator used
  - Works on 32-bit signed integers and IEEE 754 extended precision 40-bit floating-point data
- Scheduling and parallelism operations are automatically defined and managed at compile time by the assembler-optimizer, allowing efficient code execution
- Architecture is designed for efficient C-language support



# **ARM – DSP Inter-processor Communications**

- DSP is connected to ARM processor through a master AHB IF and a slave AHB IF
- ARM Processor and DSP also exchange a set of discrete lines for the cores interconnection:
  - Three external interrupt input lines that go from the external pin (through PIO) to the AIC also go to the IRQ lines in the DSP
  - Four internal interrupt lines that go from the SSC to the AIC also go to IRQ lines in the DSP
  - NINT line goes from the AIC to PMC and is the AND of the fast interrupt NFIQ and NIRQ in the ARM



# **Programming Environment for DIOPSIS 940 HF**

- Uses the standard ARM programming environment for the 926EJS
- Very little commercial support for programming the DSP exists.
  - Typical of a good number of these kinds of platforms
  - Tools were generated for the SHAPES\* effort by Target Compiler Technologies.
- DON'T FALL in LOVE with a HW ARCHITECTURE

<sup>\*</sup> Software Hardware Architecture Platform for Embedded Systems



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# **TI OMAP (Open Multimedia Applications Platform)**

- 'Platform' = Processor + Software + Support
- Uses commercially available GPP and DSP components which are scalable to future generations
- Software from application to system software
  - DSP libraries; J2ME, Linux, MS WinCE, Palm, Symbian

# Microsoft®

















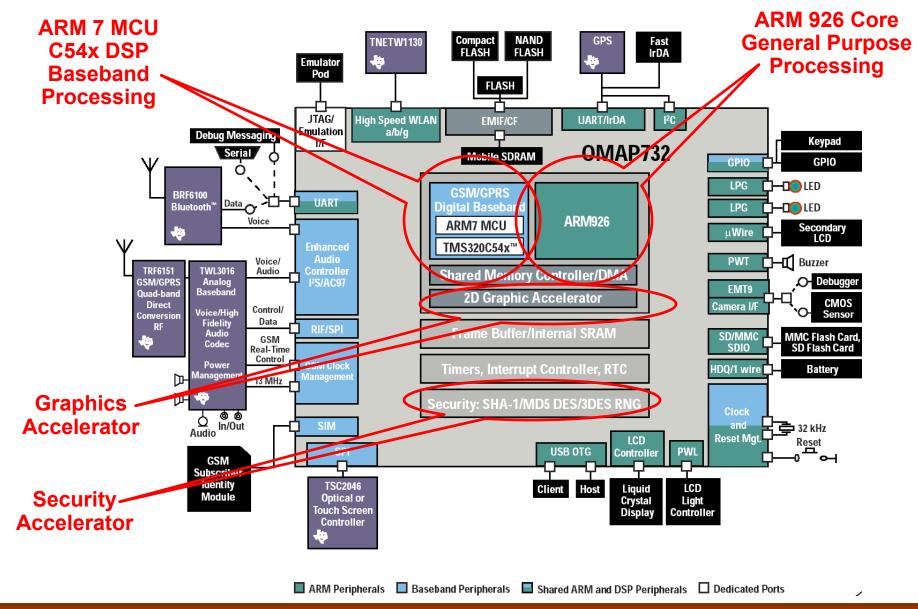








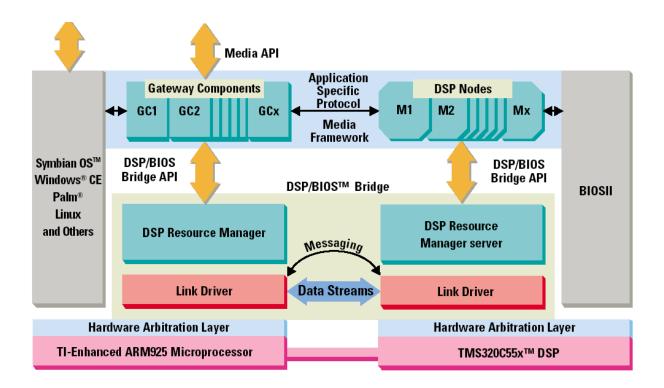
# **TI OMAP732 Hardware Platform**





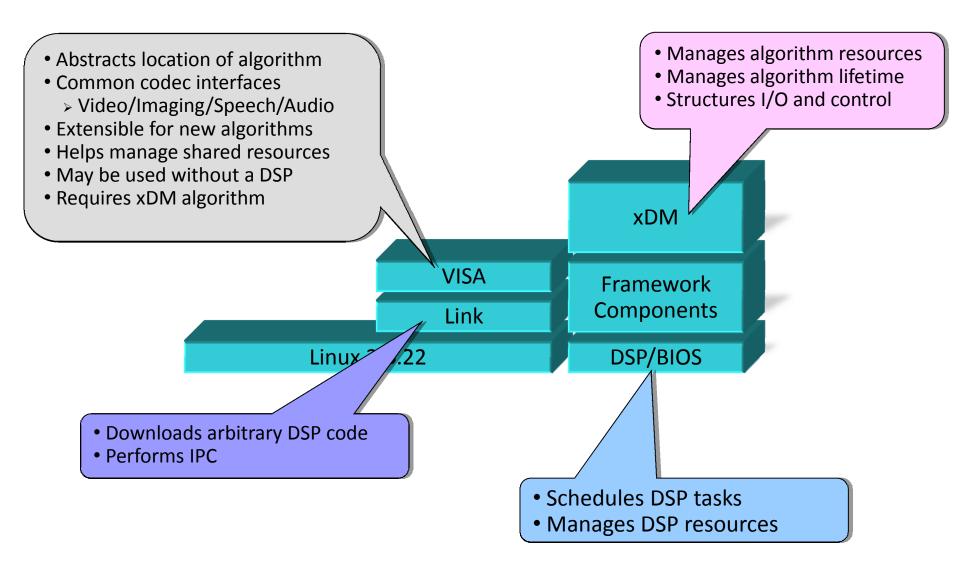
# **OMAP Programming Environment**

- DSP/BIOS bridge to divide tasks between CPU, DSP: 'reroute' some tasks to DSP and run 'asynchronously'
- Allow CPU programmer to access and control DSP runtime environment (through API)
- Code developer sees as if only a single RISC processor is doing all the functions
  - Not two different programming environments.





### **Overview of SW stacks**





# **OMAP Software**

# Drivers/OS/Apps

### **DSP Codecs**

- MPEG4 SP Encode/Decode(D1)<sup>3</sup>
- MPEG2 MP Decode(D1/)³
- H.264 MP decode / BP encode (D1)<sup>3</sup>
- WMV/VC1 Decode (D1)<sup>3</sup>
- JPEG Encode/Decode
- AAC LC Decode
- WMA9 Decode
- MP3 Decode
- AAC HE Decode

### **Development Tools**

- Code Sourcery GNU gcc 4.2.1
- glibc
- Build-root "busybox" filesystem
- U-boot 1.1.4
- Platform Builder (WinCE only)



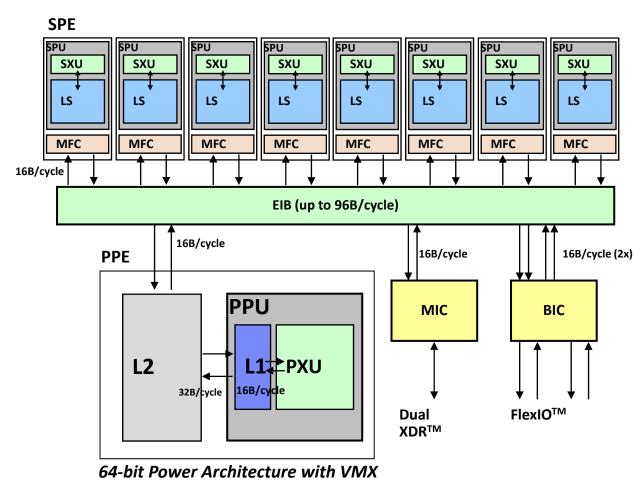
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# **IBM Cell Features**

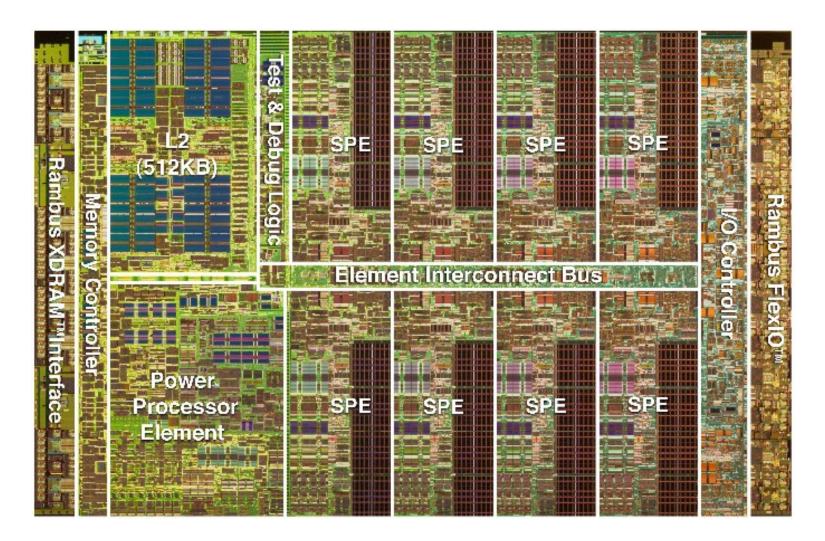
- Heterogeneous multicore system architecture
  - Power Processor Element for control tasks
  - Synergistic Processor Elements for dataintensive processing
- Synergistic Processor Element (SPE) consists of
  - Synergistic Processor Unit (SPU)
  - Synergistic Memory Flow Control (MFC)
    - Data movement and synchronization
    - Interface to highperformance
       Element
       Interconnect Bus



Courtesy IBM, Inc.



# **Cell Broadband Engine – 235mm²**



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### **Power Processor Element (PPE):**

- General purpose, 64-bit RISC processor (PowerPC AS 2.0.2)
- · 2-Way hardware multithreaded
- L1: 32KB I; 32KB D
- L2: 512KB
- Coherent load / store
- VMX-32
- Realtime Controls
  - Locking L2 Cache & TLB
  - Software / hardware managed TLB
  - Bandwidth / Resource Reservation
  - Mediated Interrupts

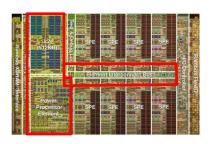
# 96 Byte/Cycle NCU Power Core (PPE) L2 Cache Element Interconnect Bus

Custom Designed

– for high frequency, space,
and power efficiency

### **Element Interconnect Bus (EIB):**

- Four 16 byte data rings supporting multiple simultaneous transfers per ring
- 96Bytes/cycle peak bandwidth
- Over 100 outstanding requests



Courtesy IBM, Inc.

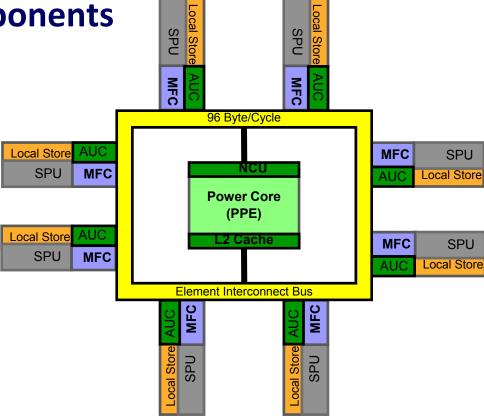


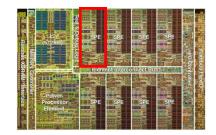
### **Synergistic Processor Element (SPE):**

- Provides the computational performance
- Simple RISC User Mode Architecture
  - Dual issue VMX-like
  - Graphics SP-Float
  - IEEE DP-Float
- Dedicated resources: unified 128x128-bit RF, 256KB Local Store
- Dedicated DMA engine: Up to 16 outstanding requests

### **Memory Management & Mapping**

- SPE Local Store aliased into PPE system memory
- MFC/MMU controls / protects SPE DMA accesses
  - Compatible with PowerPC Virtual Memory Architecture
  - SW controllable using PPE MMIO
- DMA 1,2,4,8,16,128 -> 16Kbyte transfers for I/O access
- Two queues for





Courtesy IBM, Inc.

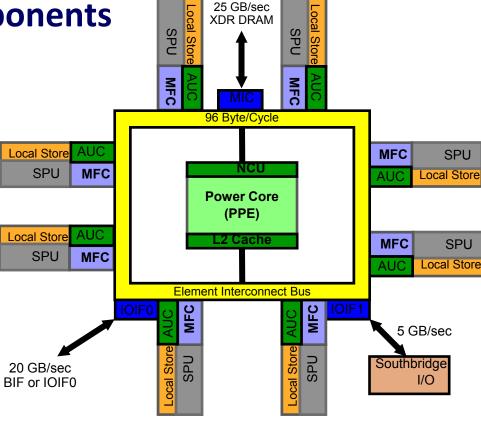


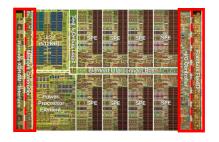
### **Broadband Interface Controller (BIC):**

- Provides a wide connection to external devices
- Two configurable interfaces (60GB/s @ 5Gbps)
  - Configurable number of bytes
  - Coherent (BIF) and / or I/O (IOIFx) protocols
- Supports two virtual channels per interface
- Supports multiple

### **Memory Interface Controller (MIC):**

- Dual XDR<sup>™</sup> controller (25.6GB/s @ 3.2Gbps)
- ECC support
- Suspend to DRAM support





Courtesy IBM, Inc.

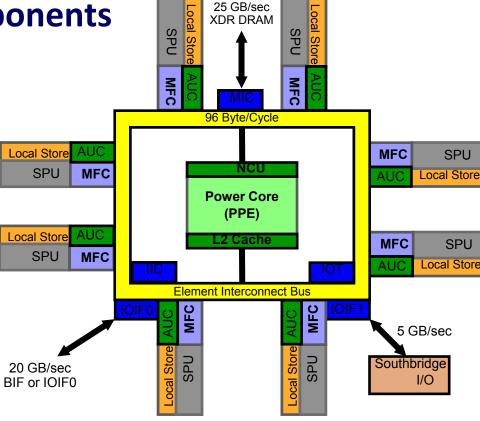


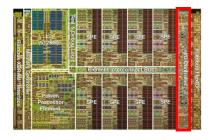
### **Internal Interrupt Controller (IIC)**

- Handles SPE Interrupts
- Handles External Interrupts
  - From Coherent Interconnect
  - From IOIF0 or IOIF1
- Interrupt Priority Level Control
- Interrupt Generation Ports for IPI
- Duplicated for each PPE hardware thread

### I/O Bus Master Translation (IOT)

- Translates Bus Addresses to System Real Addresses
- Two Level Translation
  - I/O Segments (256 MB)
  - I/O Pages (4K, 64K, 1M, 16M byte)
- I/O Device Identifier per page for LPAR
- IOST and IOPT Cache hardware / software managed



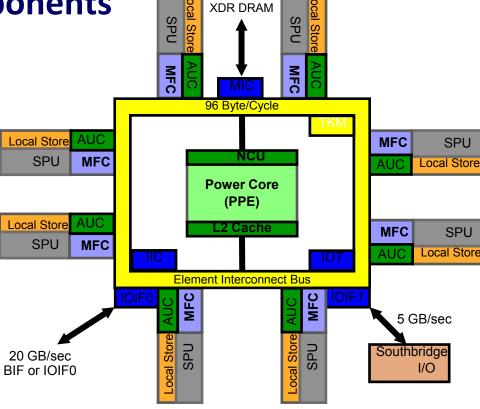


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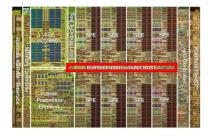


### **Token Manager (TKM):**

- Bandwidth / Resource Reservation for shared resources
- Optionally enabled for RT tasks or LPAR
- Multiple Resource Allocation Groups (RAGs)
- Generates access tokens at configurable rate for each allocation group
  - 1 per each memory bank (16 total)
  - 2 for each IOIF (4 total)
- Requestors assigned RAG ID by OS / hypervisor
  - Each SPE
  - PPE L2 / NCU
  - IOIF 0 Bus Master
  - IOIF 1 Bus Master
- Priority order for using another RAGs unused tokens
- Resource over committed warning interrupt



25 GB/sec

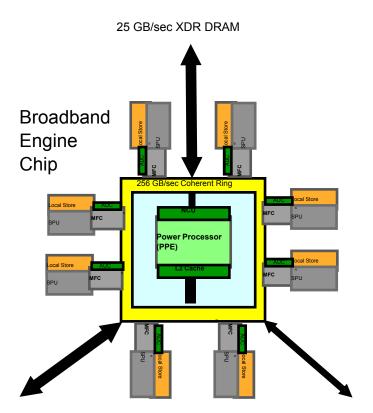


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# **Cell Broadband Engine Software Overview**

- Flexible Program Models
  - Application Accelerator Model
  - Function Offload Model
  - Computation Acceleration
  - Heterogeneous Multi-Threading Model



20 GB/sec Coherent Interconnect

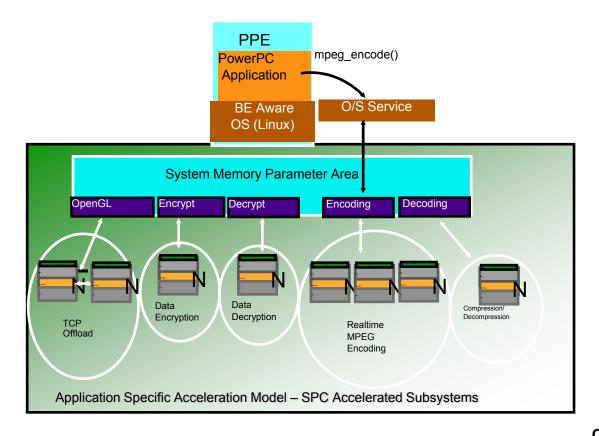
5 GB/sec I/O Bus

Courtesy IBM, Inc.



# **Programming Models**

- Application Specific Accelerators
  - Acceleration provided by O/S services
  - Application independent of accelerators platform fixed



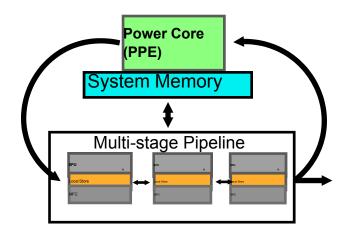
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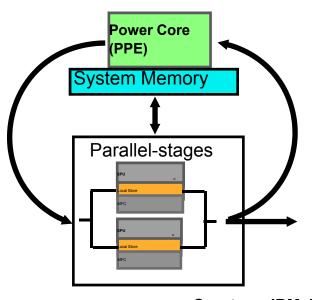


# **Subsystem Programming Model**

### Function Offload

- Dedicated Function (problem/privileged subsystem)
  - Programmer writes/uses SPU "libraries"
    - Graphics Pipeline
    - Audio Processing
    - MPEG Encoding/Decoding
    - Encryption / Decryption
  - Main Application in PPE, invokes SPU bound services
    - RPC Like Function Call
    - I/O Device Like Interface (FIFO/ Command Queue)
  - 1 or more SPUs cooperating in subsystem
    - Problem State (Application Allocated)
    - Privileged State (OS Allocated)
  - Code-to-data or data-to-code pipelining possible
  - Very efficient in real-time data streaming applications



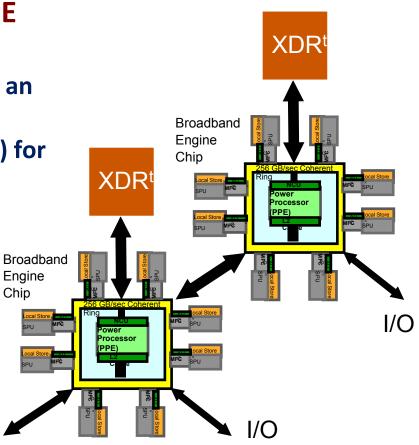


Courtesy IBM, Inc.



# **Parallel Computational Acceleration**

- Single Source Compiler (PPE and SPE targets)
  - Auto parallelization ( treat target Cell as an Shared Memory MP )
  - Auto SIMD-ization (SIMD-vectorization) for PPE VMX and SPE
  - Compiler management of Local Store as Software managed cache (I&D)
- Optimization Options
  - OpenMP-like pragmas
  - MPI based Microtasking
  - Streaming languages
  - Vector.org SIMD intrinsics
  - Data/Code partitioning
  - Streaming / pre-specifying code/data use
    - Compiler or Programmer scheduling of DMAs
    - Compiler use of Local store as soft-cache

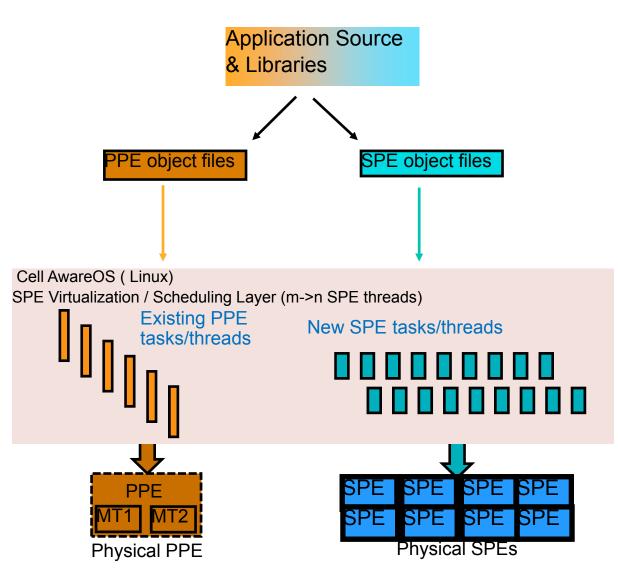


Courtesy IBM, Inc.



# **Heterogeneous Multi-Threading Model**

- PPE Threads, SPE Threads
- SPE DMA EA = PPE ProcessEA Space
  - Or SPE Private EA space
- OS supports Create/Destroy SPE tasks
- Atomic Update Primitives used for Mutex
- SPE Context Fully Managed
  - Context Save/Restore for Debug
  - Virtualization Mode (indirect access)
  - Direct Access Mode (realtime)
- OS assignment of SPE threads to SPEs
  - Programmer directed using affinity mask
- SPE Compilers use OS runtime services

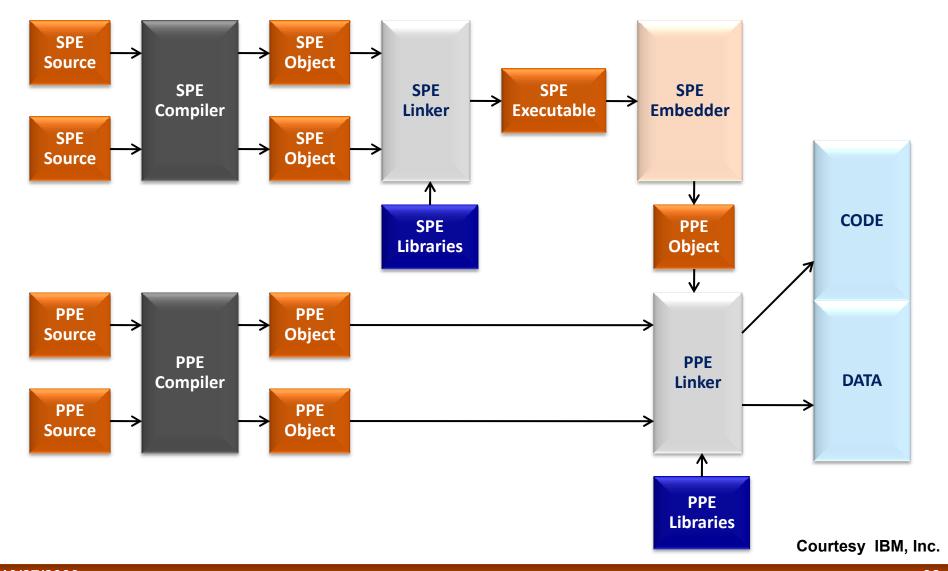


Courtesy IBM, Inc.

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# Compiling and binding a Cell BE program





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### HMC-SOC Bus Architectures

- AMBA AXI
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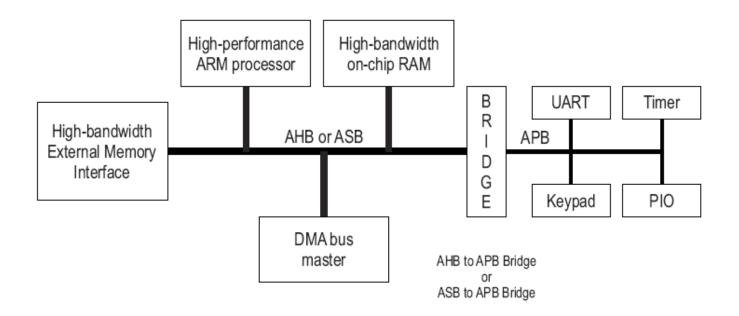


### **AMBA Introduction**

- Advanced Microcontroller Bus Architecture (AMBA), created by ARM as an interface for their microprocessors.
- Easy to obtain documentation (free download) and can be used without royalties.
- Very common in commercial SoC's (e.g. Qualcomm Multimedia Cellphone SoC)
- AMBA 2.0 released in 1999, includes APB and AHB
- AMBA 3.0 released in 2003, includes AXI



# **AMBA 2.0 System-Level View**



### AMBA AHB

- \* High performance
- \* Pipelined operation
- \* Multiple bus masters
- \* Burst transfers
- \* Split transactions

### AMBA ASB

- \* High performance
- \* Pipelined operation
- \* Multiple bus masters

### **AMBA APB**

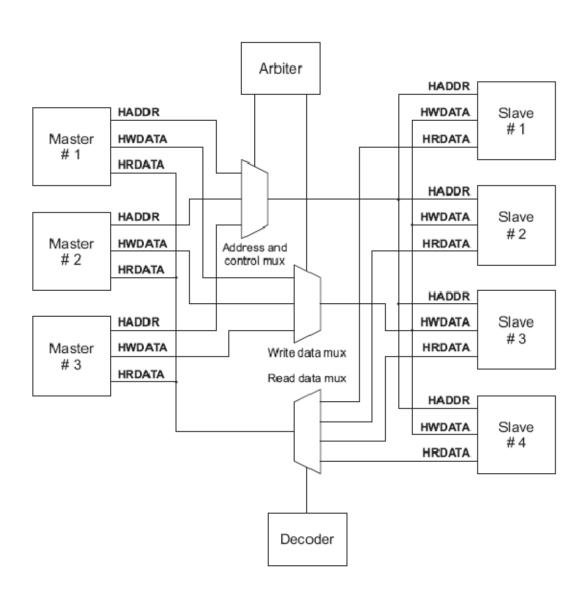
- \* Low power
- \* Latched address and control
- \* Simple interface
- \* Suitable for many peripherals

Source: AMBA Specification, Rev. 2.0



# **AHB Architecture**

- Central MUX is used, rather than a bus
- Achieves smaller delays than a single wire w/ tri-state buffers



Source: AMBA Specification, Rev. 2.0



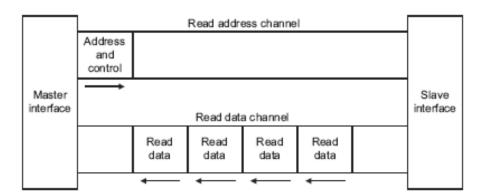
#### **AMBA 3.0**

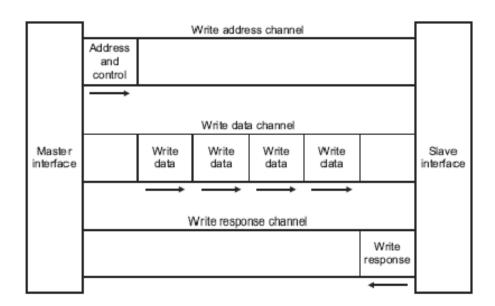
- AXI high performance protocol
  - Support for separate read address, write address, read data, write data, write response channels
  - Up to 16 masters allowed
  - Requires ~77 control signals
  - Out of order (OO) transaction completion
  - Fixed mode burst support
    - Useful for I/O peripherals
  - Advanced system cache support
    - Specify if transaction is cacheable/bufferable
    - Specify attributes such as write-back/write-through
  - Enhanced protection support
    - Secure/non-secure transaction specification
  - Exclusive access (for semaphore operations)
  - Register slice support for high frequency operation



# **Multi-Channel Support**

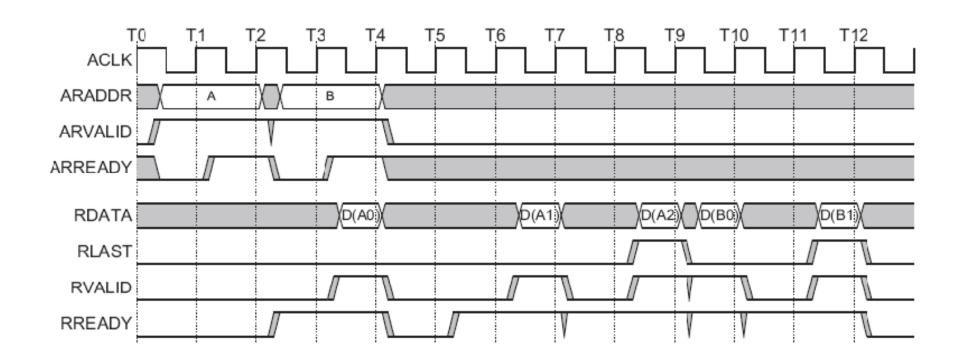
- Address, Data, and Response split between channels, rather than phases
- Allows simultaneous reads and writes





**Source: AMBA AXI Protocol Specification** 

### **AXI Read Transactions**



Up to 16 transactions can be queued at once

**Source: AMBA AXI Protocol Specification** 

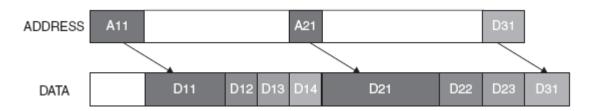


#### **AHB vs. AXI Burst**

- AHB Burst
  - Address and Data are locked together (single pipeline stage)
  - HREADY controls intervals of address and data



- AXI Burst
  - One Address for entire burst

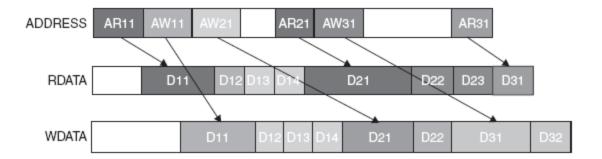




### **AHB vs. AXI Burst**

#### AXI Burst

- Simultaneous read, write transactions
- Better bus utilization

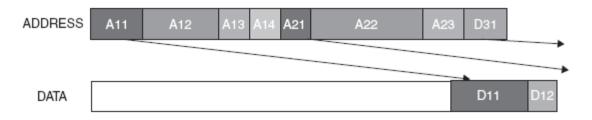




## **AXI Out of Order Completion**

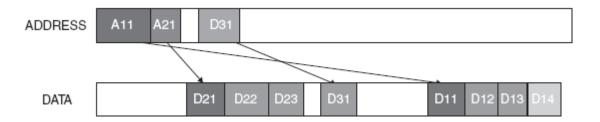
#### With AHB

- If one slave is very slow, all data is held up
- SPLIT transactions provide very limited improvement



#### With AXI Burst

- Multiple outstanding addresses, out of order (OO) completion allowed
- Fast slaves may return data ahead of slow slaves

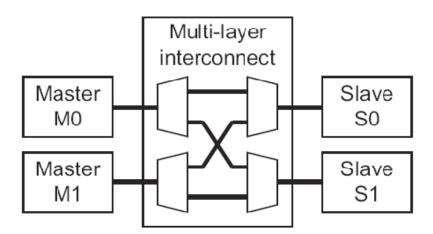


On-Chip Communication Architectures: Sudeep Pasricha & Nikil Dutt



# **Multi-Layer Connectivity**

- PL300 Interconnect is implemented as a crossbar:
- Multiple masters can talk to multiple slaves simultaneously



Source: PL300 Technical Reference Manual



# **Comparison of AMBA Bus Types**

	АРВ	AHB	AXI / PL300
Processors	all	ARM7,9,10	ARM11/Cortex
Control Signals	4	27	77
No. of Masters	1	1-15	1-16
No. of Slaves	1-15	1-15	1-16
Interconnect Type	Central MUX?	Central MUX	Crossbar w/ 5 channels
Phases	Setup, Enable	Bus request, Address, Data	Address, Data, Response
Xact. Depth	1	2	16
Burst Lengths	1	1-32	1-16
Simultaneous Read & Write	no	no	yes



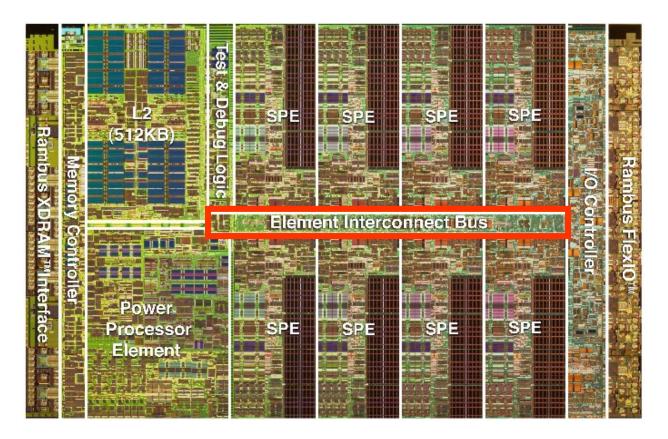
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## **Cell Broadband Processor Element Interconnect Bus (EIB)**

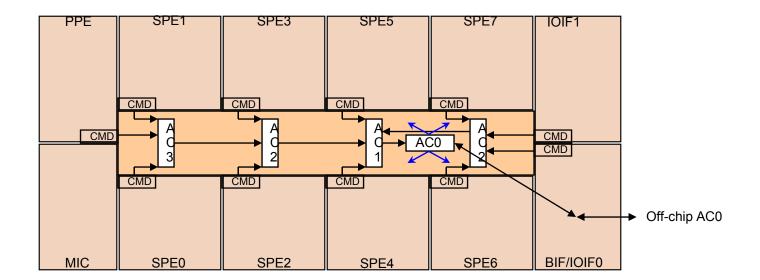
- EIB data ring for internal communication
  - Four 16 byte data rings, supporting multiple transfers
  - 96B/cycle peak bandwidth
  - Over 100 outstanding requests





# **Element Interconnect Bus – Command Topology**

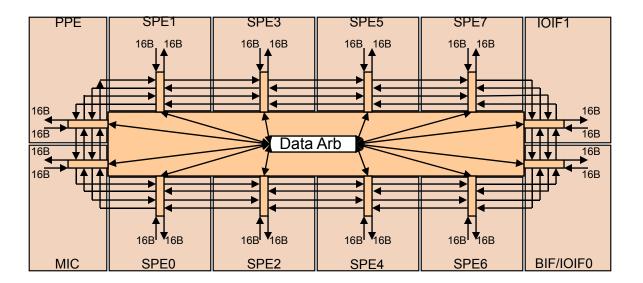
- "Address Concentrator" tree structure minimizes wiring resources
- Single serial command reflection point (AC0)
- Address collision detection and prevention
- Fully pipelined
- Content –aware round robin arbitration
- Credit-based flow control





## **Element Interconnect Bus - Data Topology**

- Four 16B data rings connecting 12 bus elements
  - Two clockwise / Two counter-clockwise
- Physically overlaps all processor elements
- Central arbiter supports up to three concurrent transfers per data ring
  - Two stage, dual round robin arbiter
- Each element port simultaneously supports 16B in and 16B out data path
  - Ring topology is transparent to element data interface





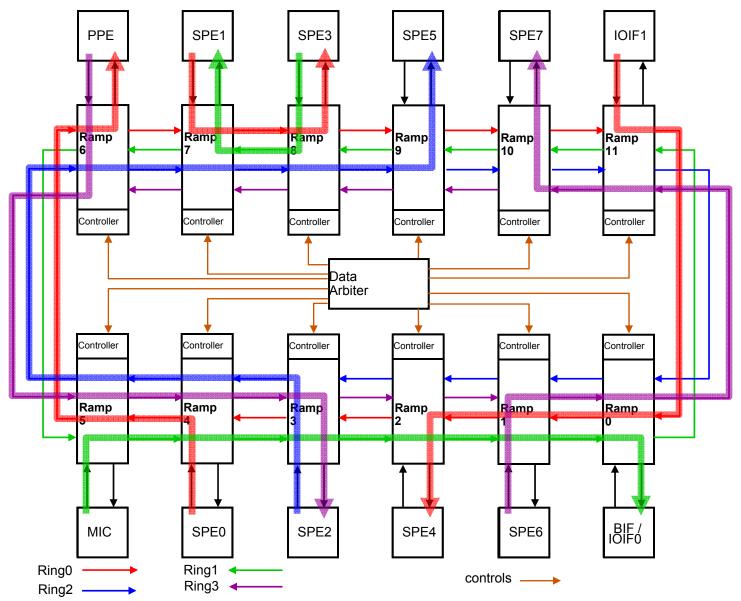
# **Internal Bandwidth Capability**

- Each EIB Bus data port supports 25.6GBytes/sec\* in each direction
- The EIB Command Bus streams commands fast enough to support 102.4 GB/sec for coherent commands, and 204.8 GB/sec for noncoherent commands.
- The EIB data rings can sustain 204.8GB/sec for certain workloads,
   with transient rates as high as 307.2GB/sec between bus units

<sup>\*</sup> The above numbers assume a 3.2GHz core frequency – internal bandwidth scales with core frequency



# **Example of eight concurrent transactions**





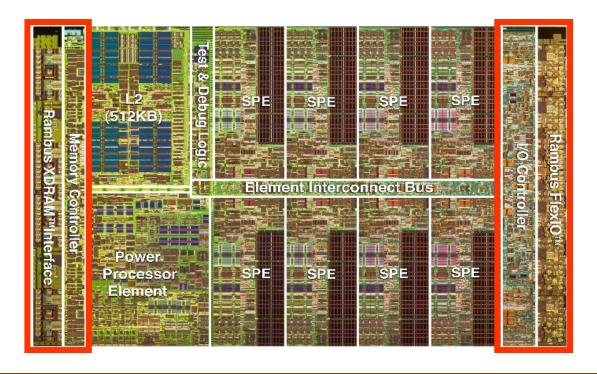
### **Resource Allocation Management**

- Optional facility used to minimize over-allocation effects of critical resources
  - Independent but complementary function to the EIB
  - Critical (managed) resource's time is distributed among groups of requestors
- Managed resources include:
  - Rambus XDR<sup>TM</sup> DRAM memory banks (0 to 15)
  - BIF/IOIF0 Inbound and BIF/IOIF0 Outbound
  - IOIF1 Inbound and IOIF1 Outbound
- Requestors Allocated to Four Resource Allocation Groups (RAG)
  - 17 requestors PPE, SPEs, I/O Inbound (4 VCs), I/O Outbound (4 VCs)
- Central Token Manager controller
  - Requestors ask permission to issue EIB commands to managed resources
  - Tokens granted across RAGs allow requestor access to issue command to the EIB
  - Round robin allocation within RAG
  - Dynamic software configuration of the Token Manager to adjust token allocation rates for varying workloads
  - Multi-level hardware feedback from managed resource congestion to throttle token allocation



# I/O and Memory Interfaces

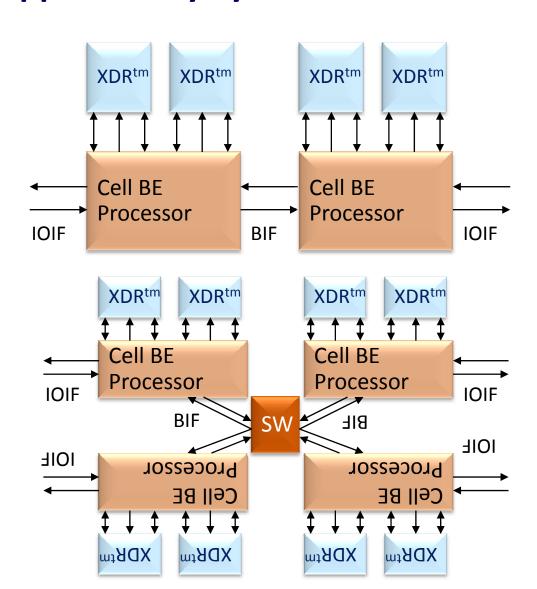
- I/O Provides wide bandwidth
  - Dual XDRTM controller (25.6GB/s @ 3.2Gbps)
  - Two configurable interfaces (76.8GB/s @6.4Gbps)
    - Configurable number of Bytes
    - Coherent or I/O Protection
  - Allows for multiple system configurations





## **Cell BE Processor Can Support Many Systems**

- Game console systems
- Blades
- HDTV
- Home media servers
- Supercomputers





# **Agenda**

- Market Prediction
- Architectures of three HMC-SOC platforms:
  - Atmel DIOPSIS 940HF SOC
  - Texas Instruments OMAP
  - IBM Cell Broadband Processor
- HMC-SOC Bus Architectures
  - AMBA AXI
  - IBM Cell Element Interconnect Bus (EIB)
  - Network on Chip Architectures (NOC)



#### **NOC Architectures**

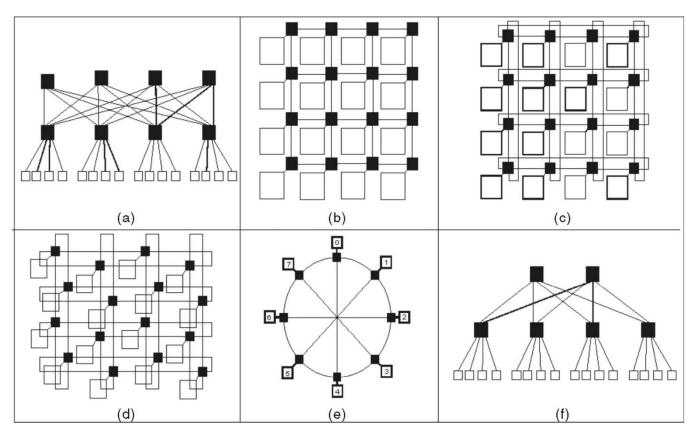
- Paradigm shift in Multi-core SOC design
- Communication challenges
  - Synchronous communication infeasible
  - Errors due to integrity issues
    - RLC effects
    - Cross-coupling effects
  - Delay Insensitive may be a better approach.
- Network-on-Chip (NoC)
  - Packet switching based communication.
  - Extremely high bandwidth by pipelined signal transmission.
  - Asynchronous (delay insensitive) communication between routers.
  - Support for error control schemes.



# **Topologies**

- Heritage of networks with new constraints
  - Need to accommodate interconnects in a 2D layout
  - Cannot route long wires (clock frequency bound)

- a) SPIN,
- b) CLICHE' & Mesh
- c) Torus
- d) Folded torus
- e) Octagon
- f) BFT



Pande, et al 2005

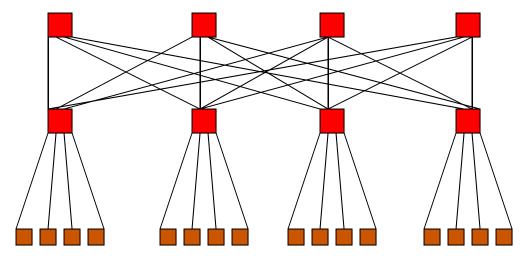


#### **Architectures: SPIN**

- SPIN: Scalable, Programmable, Integrated Network
  - Every level has same number switches
  - Network grows as (NlogN)/8
  - Trades area overhead and decreased power efficiency for higher throughput
  - Illustrative of performance vs. power consumption

**4 Equivalent Tree Roots** 

2 Stages of Routers

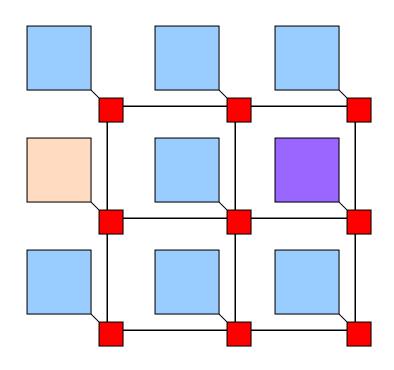


16 Terminals at the Leaves of the Tree



### **Architectures: CLICHE**

- CLICHÉ: Chip-Level Integration of Communicating Heterogeneous Elements
  - Two-dimensional mesh network layout for NoC design
  - All switches are connected to the four closest other switches and target resource block, except those switches on the edge of the layout
  - Connections are two unidirectional links

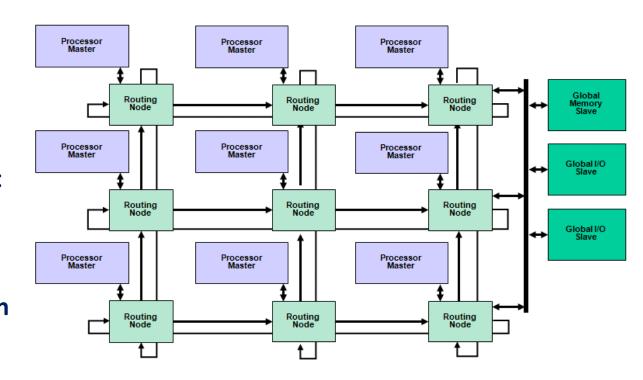




### **Architectures: Torus**

### Similar to mesh based architectures

- Wires are wrapped around from the top component to the bottom and rightmost to leftmost
- Smaller hop count
- Higher bandwidth
- Decreased Contention
- Increased chip space usage

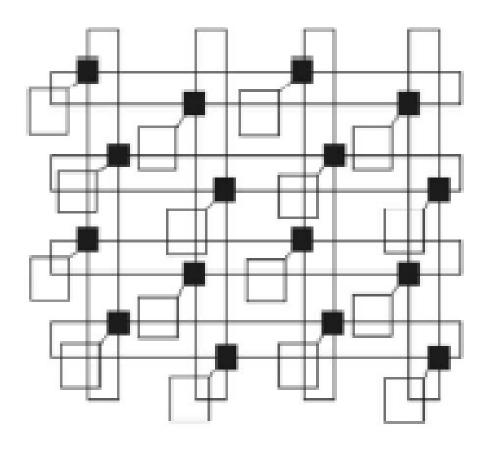




### **Architectures: Folded Torus**

#### Similar to Torus

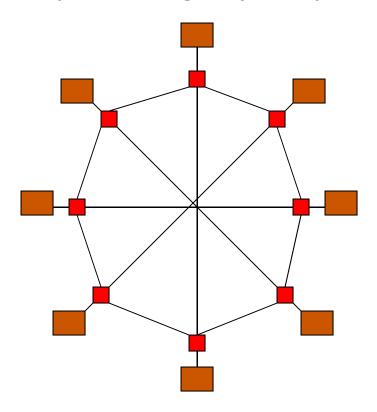
- Torus, the long end-around connections can yield excessive delays
- Avoided by folding the torus

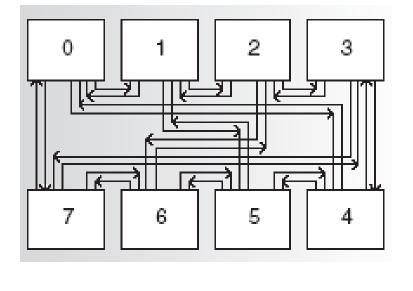




# **Architectures: Octagon**

- Standard model: 8 components, 12 interconnects
  - Design complexity increases linearly with number of nodes
  - Largest packet travel distance is two hops
  - High throughput
  - Shortest path routing easy to implement



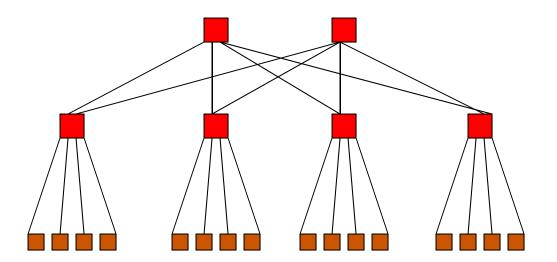




### **Architectures: BFT**

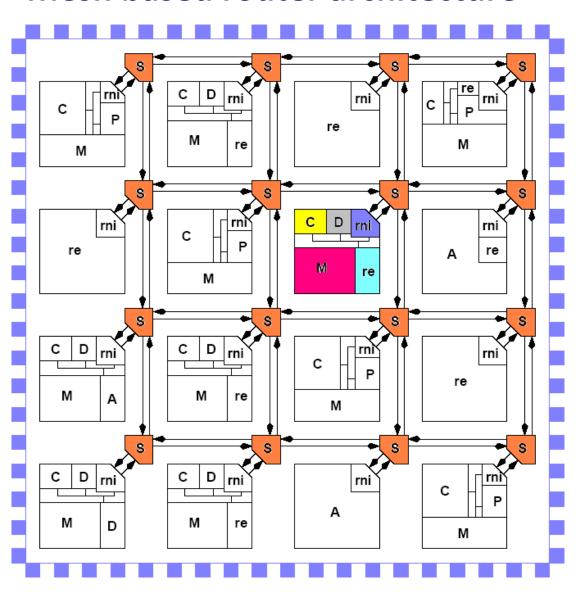
#### BFT: Butterfly Fat Tree

- Each node in tree model has coordinates (level, position) where level is depth and position is from left to right
- Leaves are component blocks
- Interior nodes are switches
- Four child ports per switch and two parent ports
- LogN levels, ith level has n/(2^i+1) switches, n = leaves (blocks)
- Use traffic aggregation to reduce congestion





### Mesh based router architecture



S = switch/router

rni = resource network interface

C = cache

P = processor

M = memory

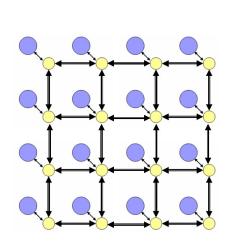
D = DSP

re = reconfigurable logic

Chatha, ASU, 2005

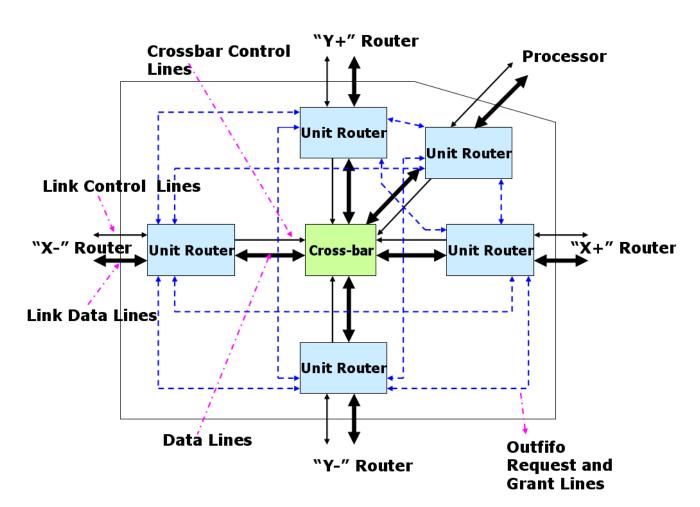


### Mesh based router architecture



Router

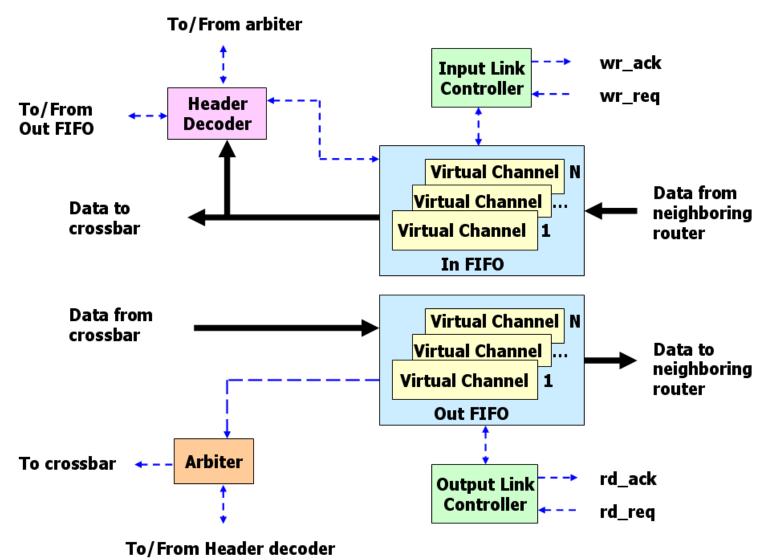
Processor



Chatha, ASU, 2005



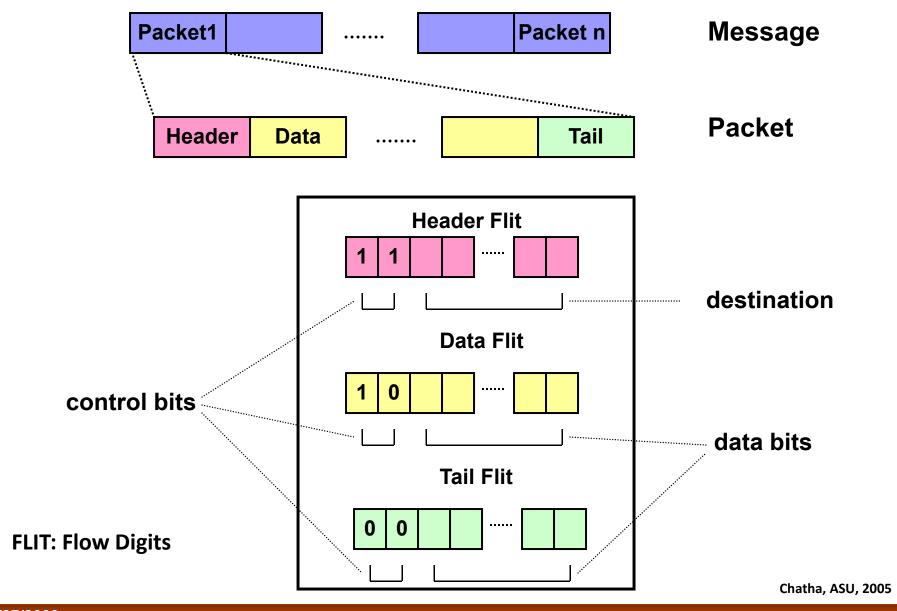
### **Unit Router Architecture**



Chatha, ASU, 2005



### **Packet Format**





## **Routing Performance metrics**

#### Injection Rate

 Number of packets that are injected from the source into the network per unit time

### Average Network Latency

 Average delay experienced by packets as they traverse from source to destination.

#### Average Setup Latency

 Average time required to reserve the virtual channels for the GT traffic from source to destination.

#### Acceptance rate

 Number of packets reaching each of the destination nodes per clock cycle at a particular injection rate.

### Average power consumption

 Sum of average dynamic and leakage power consumed by the network per clock cycle.

Chatha, ASU, 2005



# **Quality-of-Service levels**

- Guaranteed Throughput (GT)
  - Throughput and latency guarantees
  - Supports bursty traffic
  - 3 stages setup, transmit, tear-down
    - setup virtual channels reserved from source to destination
    - transmit packets transferred with maximum throughput
    - tear-down path is set free
- Best Effort (BE)
  - no time guarantees



## **Quality-of-Service architecture**

- Virtual channels divided into two sets
  - Guaranteed throughput and best effort
  - GT traffic can take over BE virtual channels
- Higher priority given to GT traffic
  - Header decoder
  - Arbiter
  - Output link controller
- Round-robin priority mechanism within each class